



RESPONSE UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE

IN THE U.S. PATENT AND TRADEMARK OFFICE

April 21, 2003

Applicants: Motohide TAKEICHI et al

For: COG-ASSEMBLY AND  
CONNECTING MATERIAL TO BE USED THEREIN

Serial No.: 09/659 448

Group: 2827

Confirmation No.: 5818

Filed: September 11, 2000

Examiner: Graybill

Atty. Docket No.: Yanagihara Case 52

Box AF

Assistant Commissioner for Patents  
Washington, DC 20231

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TECHNOLOGY CENTER 2800

**AMENDMENT AFTER FINAL REJECTION**

Sir:

In response to the Office Action dated October 21, 2002,  
Applicants respectfully request entry of the following  
amendments:

**IN THE CLAIMS**

Please amend Claims 8 and 9 as follows. A marked-up copy  
is enclosed.

8. (Amended) A connecting material for bonding and  
connecting a semiconductor chip with a substrate glass board  
and forming a COG assembly in which electrodes provided on the  
semiconductor chip are held in direct connection with  
corresponding electrodes provided on the substrate glass  
board, said connecting material having a tensile elongation  
percentage at 25°C of at least 5%, after being cured, and  
comprising:

an adhesive component comprising a thermosetting resin  
and 6-90 wt.% of a microparticulate elastomer product of  
natural or synthetic rubber having an average particle size of  
30-300 nm and

electroconductive particles.